

Product Change Notification - KSRA-23UQZO342

Date: 03 Mar 2017
Notification subject: CCB 2874 Initial Notice: Qualification of CuPdAu bond wire for selected products of 250K and 290K wafer technology available in 14L TSSOP package at MMT assembly site
Notification text: **PCN Status:**
 Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 250K and 290K wafer technology available in 14L TSSOP package at MMT assembly site.

Pre Change:

Assembled using gold (Au) bond wire

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT	MMT
Wire material	Au wire	CuPdAu wire
Die attach material	2200D	2200D
Molding compound material	G600V	G600V
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date

May 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

Workweek	March 2017					-->	May 2017				
	09	10	11	12	13		18	19	20	21	22
Initial PCN Issue Date	X										
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
March 03, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_KSRA-23UQZO342_Affected CPN.pdf](#)
 - [PCN_KSRA-23UQZO342_Qual Plan.pdf](#)
 - [PCN_KSRA-23UQZO342_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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PCN_KSRA-23UQZO342 -CCB 2874: Initial Notice: Qualification of CuPdAu bond wire for selected products of 290K wafer technology available in 14L TSSOP package at MMT assembly site

Affected Catalog Part Number (CPN)

PCN_KSRA-23UQZO342
CatalogPartNumber
PIC16F15324-E/ST
PIC16F15324-I/ST
PIC16F15324T-E/ST
PIC16F15324T-I/ST
PIC16F15325-E/ST
PIC16F15325-I/ST
PIC16F15325T-I/ST
PIC16F18323-E/ST
PIC16F18323-I/ST
PIC16F18323T-E/ST
PIC16F18323T-I/ST
PIC16F18324-E/ST
PIC16F18324-I/ST
PIC16F18324T-I/ST
PIC16F18325-E/ST
PIC16F18325-I/ST
PIC16F18325T-I/ST
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